FUNDAMENTALS OF SEMICONDUCTOR MANUFACTURING AND PROCESS CONTROL

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CONTENTS

Preface xvii

Acknowledgments xix

1 Introduction to Semiconductor Manufacturing 1

Objectives / 1
Introduction / 1
1.1. Historical Evolution / 2
1.1.1. Manufacturing and Quality Control / 3
1.1.2. Semiconductor Processes / 5
1.1.3. Integrated Circuit Manufacturing / 7
1.2. Modern Semiconductor Manufacturing / 8
1.2.1. Unit Processes / 9
1.2.2. Process Sequences / 11
1.2.3. Information Flow / 12
1.2.4. Process Organization / 14
1.3. Goals of Manufacturing / 15
1.3.1. Cost / 15
1.3.2. Quality / 17
1.3.3. Variability / 17
1.3.4. Yield / 17
1.3.5. Reliability / 18
1.4. Manufacturing Systems / 18
1.4.1. Continuous Flow / 19
1.4.1.1. Batch Processes / 20
1.4.1.2. Single Workpiece / 20
1.4.2. Discrete Parts / 21
1.5. Outline for Remainder of the Book / 21
Summary / 22
Problems / 22
References / 23

2 Technology Overview **25**

Objectives / 25
Introduction / 25
2.1. Unit Processes / 25
2.1.1. Oxidation / 26
2.1.1.1. Growth Kinetics / 27
2.1.1.2. Thin Oxide Growth / 31
2.1.1.3. Oxide Quality / 33
2.1.2. Photolithography / 34
2.1.2.1. Exposure Tools / 35
2.1.2.2. Masks / 38
2.1.2.3. Photoresist / 39
2.1.2.4. Pattern Transfer / 41
2.1.2.5. E-Beam Lithography / 43
2.1.2.6. X-Ray Lithography / 45
2.1.3. Etching / 47
2.1.3.1. Wet Chemical Etching / 47
2.1.3.2. Dry Etching / 48
2.1.4. Doping / 51
2.1.4.1. Diffusion / 52
2.1.4.2. Ion Implantation / 56
2.1.5. Deposition / 58
2.1.5.1. Physical Vapor Deposition / 59
2.1.5.2. Chemical Vapor Deposition / 60
2.1.6. Planarization / 61
2.2. Process Integration / 61
2.2.1. Bipolar Technology / 63
2.2.2. CMOS Technology / 66
2.2.2.1. Basic NMOS Fabrication Sequence / 67
2.2.2.2. CMOS Fabrication Sequence / 70
2.2.3. BiCMOS Technology / 74
2.2.4. Packaging / 75
2.2.4.1. Die Separation / 76
2.2.4.2. Package Types / 77
2.2.4.3. Attachment Methods / 79
Summary / 80
Problems / 80
References / 81

3 Process Monitoring **82**

Objectives / 82
Introduction / 82
3.1. Process Flow and Key Measurement Points / 83
3.2. Wafer State Measurements / 84
3.2.1. Blanket Thin Film / 85
3.2.1.1. Interferometry / 85
3.2.1.2. Ellipsometry / 88
3.2.1.3. Quartz Crystal Monitor / 91
3.2.1.4. Four-Point Probe / 92
3.2.2. Patterned Thin Film / 93
3.2.2.1. Profilometry / 93
3.2.2.2. Atomic Force Microscopy / 93
3.2.2.3. Scanning Electron Microscopy / 95
3.2.2.4. Scatterometry / 96
3.2.2.5. Electrical Linewidth Measurement / 98
3.2.3. Particle/Defect Inspection / 98
3.2.3.1. Cleanroom Air Monitoring / 99
3.2.3.2. Product Monitoring / 100
3.2.4. Electrical Testing / 102
3.2.4.1. Test Structures / 102
3.2.4.2. Final Test / 106
3.3. Equipment State Measurements / 107
3.3.1. Thermal Operations / 109
3.3.1.1. Temperature / 109
3.3.1.2. Pressure / 109
3.3.1.3. Gas Flow / 110
3.3.2. Plasma Operations / 111
3.3.2.1. Temperature / 111
3.3.2.2. Pressure / 112
3.3.2.3. Gas Flow / 112
3.3.2.4. Residual Gas Analysis / 112
3.3.2.5. Optical Emission Spectroscopy / 114
3.3.2.6. Fourier Transform Infrared Spectroscopy / 115
3.3.2.7. RF Monitors / 116
3.3.3. Lithography Operations / 116
3.3.4. Implantation / 117

3.3.5. Planarization / 118
Summary / 118
Problems / 119
References / 120

4 **Statistical Fundamentals** **122**

Objectives / 122
Introduction / 122
4.1. Probability Distributions / 123
4.1.1. Discrete Distributions / 124
4.1.1.1. Hypergeometric / 124
4.1.1.2. Binomial / 125
4.1.1.3. Poisson / 127
4.1.1.4. Pascal / 128
4.1.2. Continuous Distributions / 128
4.1.2.1. Normal / 129
4.1.2.2. Exponential / 131
4.1.3. Useful Approximations / 132
4.1.3.1. Poisson Approximation to the Binomial / 132
4.1.3.2. Normal Approximation to the Binomial / 132
4.2. Sampling from a Normal Distribution / 133
4.2.1. Chi-Square Distribution / 134
4.2.2. t Distribution / 134
4.2.3. F Distribution / 135
4.3. Estimation / 136
4.3.1. Confidence Interval for the Mean with Known Variance / 137
4.3.2. Confidence Interval for the Mean with Unknown Variance / 137
4.3.3. Confidence Interval for Variance / 137
4.3.4. Confidence Interval for the Difference between Two Means, Known Variance / 138
4.3.5. Confidence Interval for the Difference between Two Means, Unknown Variances / 138
4.3.6. Confidence Interval for the Ratio of Two Variances / 139
4.4. Hypothesis Testing / 140
4.4.1. Tests on Means with Known Variance / 141
4.4.2. Tests on Means with Unknown Variance / 142
4.4.3. Tests on Variance / 143

Summary / 145
Problems / 145
Reference / 146

5 Yield Modeling **147**

Objectives / 147
Introduction / 147
5.1. Definitions of Yield Components / 148
5.2. Functional Yield Models / 149
5.2.1. Poisson Model / 151
5.2.2. Murphy's Yield Integral / 152
5.2.3. Negative Binomial Model / 154
5.3. Functional Yield Model Components / 156
5.3.1. Defect Density / 156
5.3.2. Critical Area / 157
5.3.3. Global Yield Loss / 158
5.4. Parametric Yield / 159
5.5. Yield Simulation / 161
5.5.1. Functional Yield Simulation / 162
5.5.2. Parametric Yield Simulation / 167
5.6. Design Centering / 171
5.6.1. Acceptability Regions / 172
5.6.2. Parametric Yield Optimization / 173
5.7. Process Introduction and Time-to-Yield / 174
Summary / 176
Problems / 177
References / 180

6 Statistical Process Control **181**

Objectives / 181
Introduction / 181
6.1. Control Chart Basics / 182
6.2. Patterns in Control Charts / 184
6.3. Control Charts for Attributes / 186
6.3.1. Control Chart for Fraction Nonconforming / 187
6.3.1.1. Chart Design / 188
6.3.1.2. Variable Sample Size / 189
6.3.1.3. Operating Characteristic and Average Runlength / 191
6.3.2. Control Chart for Defects / 193
6.3.3. Control Chart for Defect Density / 193

6.4. Control Charts for Variables / 195
6.4.1. Control Charts for $\overline{x}$ and R / 195
6.4.1.1. Rational Subgroups / 199
6.4.1.2. Operating Characteristic and Average Runlength / 200
6.4.2. Control Charts for $\overline{x}$ and s / 202
6.4.3. Process Capability / 204
6.4.4. Modified and Acceptance Charts / 206
6.4.5. Cusum Chart / 208
6.4.5.1. Tabular Cusum Chart / 210
6.4.5.2. Average Runlength / 210
6.4.5.3. Cusum for Variance / 211
6.4.6. Moving-Average Charts / 212
6.4.6.1. Basic Moving-Average Chart / 212
6.4.6.2. Exponentially Weighted Moving-Average Chart / 213
6.5. Multivariate Control / 215
6.5.1. Control of Means / 217
6.5.2. Control of Variability / 220
6.6. SPC with Correlated Process Data / 221
6.6.1. Time-Series Modeling / 221
6.6.2. Model-Based SPC / 223
Summary / 224
Problems / 224
References / 227

7 Statistical Experimental Design 228

Objectives / 228
Introduction / 228
7.1. Comparing Distributions / 229
7.2. Analysis of Variance / 232
7.2.1. Sums of Squares / 232
7.2.2. ANOVA Table / 234
7.2.2.1. Geometric Interpretation / 235
7.2.2.2. ANOVA Diagnostics / 237
7.2.3. Randomized Block Experiments / 240
7.2.3.1. Mathematical Model / 242
7.2.3.2. Diagnostic Checking / 243
7.2.4. Two-Way Designs / 245
7.2.4.1. Analysis / 245
7.2.4.2. Data Transformation / 246

7.3. Factorial Designs / 249
7.3.1. Two-Level Factorials / 250
7.3.1.1. Main Effects / 251
7.3.1.2. Interaction Effects / 251
7.3.1.3. Standard Error / 252
7.3.1.4. Blocking / 254
7.3.2. Fractional Factorials / 256
7.3.2.1. Construction of Fractional Factorials / 256
7.3.2.2. Resolution / 257
7.3.3. Analyzing Factorials / 257
7.3.3.1. The Yates Algorithm / 258
7.3.3.2. Normal Probability Plots / 258
7.3.4. Advanced Designs / 260
7.4. Taguchi Method / 262
7.4.1. Categorizing Process Variables / 263
7.4.2. Signal-to-Noise Ratio / 264
7.4.3. Orthogonal Arrays / 264
7.4.4. Data Analysis / 266
Summary / 269
Problems / 269
References / 271

8 Process Modeling 272

Objectives / 272
Introduction / 272
8.1. Regression Modeling / 273
8.1.1. Single-Parameter Model / 274
8.1.1.1. Residuals / 275
8.1.1.2. Standard Error / 276
8.1.1.3. Analysis of Variance / 276
8.1.2. Two-Parameter Model / 277
8.1.2.1. Analysis of Variance / 279
8.1.2.2. Precision of Estimates / 279
8.1.2.3. Linear Model with Nonzero Intercept / 280
8.1.3. Multivariate Models / 283
8.1.4. Nonlinear Regression / 285
8.1.5. Regression Chart / 287
8.2. Response Surface Methods / 289
8.2.1. Hypothetical Yield Example / 289

8.2.1.1. Diagnostic Checking / 292
8.2.1.2. Augmented Model / 293
8.2.2. Plasma Etching Example / 294
8.2.2.1. Experimental Design / 295
8.2.2.2. Experimental Technique / 297
8.2.2.3. Analysis / 298
8.3. Evolutionary Operation / 301
8.4. Principal-Component Analysis / 306
8.5. Intelligent Modeling Techniques / 310
8.5.1. Neural Networks / 310
8.5.2. Fuzzy Logic / 314
8.6. Process Optimization / 318
8.6.1. Powell's Algorithm / 318
8.6.2. Simplex Method / 320
8.6.3. Genetic Algorithms / 323
8.6.4. Hybrid Methods / 325
8.6.5. PECVD Optimization: A Case Study / 326
Summary / 327
Problems / 328
References / 331

9 Advanced Process Control **333**

Objectives / 333
Introduction / 333
9.1. Run-by-Run Control with Constant Term Adaptation / 335
9.1.1. Single-Variable Methods / 335
9.1.1.1. Gradual Drift / 337
9.1.1.2. Abrupt Shifts / 339
9.1.2. Multivariate Techniques / 343
9.1.2.1. Exponentially Weighted Moving-Average (EWMA) Gradual Model / 343
9.1.2.2. Predictor–Corrector Control / 343
9.1.3. Practical Considerations / 346
9.1.3.1. Input Bounds / 346
9.1.3.2. Input Resolution / 348
9.1.3.3. Input Weights / 348
9.1.3.4. Output Weights / 350
9.2. Multivariate Control with Complete Model Adaptation / 351
9.2.1. Detection of Process Disturbances via Model-Based SPC / 352

9.2.1.1. Malfunction Alarms / 352
9.2.1.2. Alarms for Feedback Control / 353
9.2.2. Full Model Adaptation / 354
9.2.3. Automated Recipe Generation / 356
9.2.4. Feedforward Control / 358
9.3. Supervisory Control / 359
9.3.1. Supervisory Control Using Complete Model Adaptation / 359
9.3.1.1. Acceptable Input Ranges of Photolithographic Machines / 361
9.3.1.2. Experimental Examples / 363
9.3.2. Intelligent Supervisory Control / 364
Summary / 373
Problems / 373
References / 378

10 Process and Equipment Diagnosis 379

Objectives / 379
Introduction / 379
10.1. Algorithmic Methods / 381
10.1.1. Hippocrates / 381
10.1.1.1. Measurement Plan / 382
10.1.1.2. Fault Diagnosis / 383
10.1.1.3. Example / 383
10.1.2. MERLIN / 384
10.1.2.1. Knowledge Representation / 385
10.1.2.2. Inference Mechanism / 387
10.1.2.3. Case Study / 390
10.2. Expert Systems / 391
10.2.1. PIES / 391
10.2.1.1. Knowledge Base / 393
10.2.1.2. Diagnostic Reasoning / 394
10.2.1.3. Examples / 395
10.2.2. PEDX / 395
10.2.2.1. Architecture / 396
10.2.2.2. Rule-Based Reasoning / 397
10.2.2.3. Implementation / 398
10.3. Neural Network Approaches / 398
10.3.1. Process Control Neural Network / 398
10.3.2. Pattern Recognition in CVD Diagnosis / 400
10.4. Hybrid Methods / 402

10.4.1. Time-Series Diagnosis / 402
10.4.2. Hybrid Expert System / 403
10.4.2.1. Dempster–Shafer Theory / 406
10.4.2.2. Maintenance Diagnosis / 408
10.4.2.3. Online Diagnosis / 409
10.4.2.4. Inline Diagnosis / 413
Summary / 414
Problems / 414
References / 415

Appendix A: Some Properties of the Error Function **417**
Appendix B: Cumulative Standard Normal Distribution **420**
Appendix C: Percentage Points of the χ^2 Distribution **423**
Appendix D: Percentage Points of the *t* Distribution **425**
Appendix E: Percentage Points of the *F* Distribution **427**
Appendix F: Factors for Constructing Variables Control Charts **438**
Index **441**